Kemet

DUAL FACE GRINDING ,LAPPING & POLISHING MACHINE

Kemet Dual Face Machines grind, lap & polish both flat faces of the components at the same time.

Able to process a wide range of materials and achieve very tight tolerance and consistently

- 5 carriers are driven for smooth action when grinding or lapping fragile parts
- Plate and carrier speeds variable through AC frequency inverters.
- Custom Fine Grinding, Grinding or Lapping plates are available for optimum operation.



Options

- Automatic Thickness Control
- Load Cell Pressure Control
- HMI Touch Panel Control

Specification	DS 6	DS 9	DS 12
Diameter Of Lapping Plate (mm)	Dia. 374 x ID 150	Dia. 630 x ID 245	Dia. 762 x ID 270
Maximum Diameter Of Products (mm)	Dia. 112	Dia. 192.5	Dia. 246
Diameter Of Carrier (PCD)	Dia. 139.6 (PCD)	Dia. 228.5 (PCD)	Dia. 283.6 (PCD)
Number Of Carrier	5 Pcs	5 Pcs	5 Pcs
Minimum Thickness Of Products	0.08mm	0.3mm	0.3mm
Rotating Speed of Lower Lapping Plate (RPM)	0 ~ 60 RPM	0 ~ 60 RPM	0 ~ 60 RPM
Reversal mechanism Of Carrier	CW & CCW	CW & CCW	CW & CCW
Estimated Size	1430 x 900 x 2130	1820 x 1232 x 2280	1934 x 1445 x 2615
Weight	1300KGS	1800KGS	2300KGS
Electric Supply	380/415V 3Ph 50/60Hz	380/415V 3Ph 50/60Hz	380/415V 3Ph 50/60Hz

NOTE : In the interests of development we reserve the right to change specification without notice.
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